

AMENDMENT TRANSMITTAL LETTER

Docket No.
M4065.0223/P223Application No.
09/517,314Filing Date
March 2, 2000Examiner
D. KangArt Unit
2811

Applicant(s): Chih-chen Cho

Invention: BACKEND METALLIZATION METHOD AND DEVICE OBTAINED THEREFROM

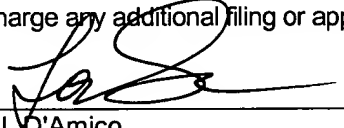
TO THE COMMISSIONER FOR PATENTS

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED

	Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present	Rate	
Total Claims	23	- 31 =		x	0.00
Independent Claims	3	- 4 =		x	0.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					
Other fee (please specify):					
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT:					

☒ Large Entity☐ Small Entity☐ No additional fee is required for this amendment.☐ Please charge Deposit Account No. _____ in the amount of \$ _____.
A duplicate copy of this sheet is enclosed.☐ A check in the amount of \$ _____ to cover the filing fee is enclosed.☐ Payment by credit card. Form PTO-2038 is attached.☒ The Commissioner is hereby authorized to charge and credit Deposit Account No. 04-1073
as described below. A duplicate copy of this sheet is enclosed.☒ Credit any overpayment.☒ Charge any additional filing or application processing fees required under 37 CFR 1.16 and 1.17.

 Thomas J. D'Amico
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Dated: September 11, 2002

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BEST AVAILABLE

Docket No.: M4065.0223/P223
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Chih-Chen Cho

Application No.: 09/517,314

Group Art Unit: 2811

Filed: March 2, 2000

Examiner: Donghee Kang

For: BACKEND METALLIZATION METHOD
AND DEVICE OBTAINED THEREFROM

#22/D
9-21-02
Payton

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PRELIMINARY AMENDMENT

Box Non-Fee Amendment
Commissioner for Patents
Washington, DC 20231

Dear Sir:

Prior to continued prosecution, please amend the above-identified U.S. patent application as follows:

In the Claims:

Please amend claims 1, 11, and 25 to read as follows.

1. (Twice Amended) A semiconductor device comprising:

an insulator layer;

a conductive plug positioned within said insulator layer and formed of a single conductive material;

a doped region connected to said conductive plug;

an etch-stop layer located on said insulator layer and surrounding said plug;